PSA Tape

Our PSA adhesive tapes, also known as TAT, are thermo-conductive silicone-based materials that solve heat dissipation problems. The TAT_010_M is an electrically insulating thermally conductive silicone PSA transfer tape. Thanks to the thermally conductive adhesive, the thermal contact is greatly improved even at low pressure. Convex and concave surface structures and stacking tolerances are effectively compensated. The tape works well to achieve efficient and cost-effective thermal coupling in a wide range of applications. Especially, it is used in applications with little space only and where the allowed weight is limited We can cut according to customer plan. All our mattresses are certified UL 94 in V0.

Domaines d'applications: Electronic components - Electric Vehicles, 5G, Autopilot System, Mobile Phone, AIOT, HPC (High Performance Computing), Server, IC, CPU, MOS, LED ,Mother Board, Power Supply, Heat Sink, LCD-TV, Notebook, PC, Telecom Device,Wireless Hub, DDR ll Module, etc.

Caractéristiques techniques

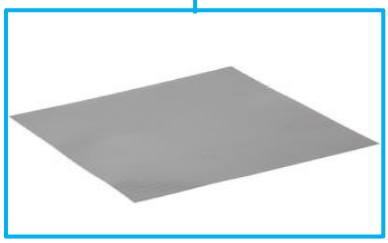
Features	Units	TAT_010_M			
Thickness	mm	0.1	0.2	-	-
Reinforcement	-	-			
Color	-	White			
Peel resistance (at 23°C) Aluminum / Glass	N/cm	6.0 / 7.6	6.4 / 7.6	-	-
Size	mm	300*400		Roll 300mm x 50M	
Shear strength (at 125°C after 10,000 hours)	N/cm	> 200		-	
Thermal Conductivity	W/mK	1.0			
Resistance	°C-inch²/W	0.28	0.49	-	
Breakdown Voltage (@ Initial Thickness, 25°C)	kV/AC	2.0	5.0	-	-

The TAT_010_M is available in 0.10/0.20mm thicknesses.

The results were obtained under laboratory conditions and should be considered only as a guide. As AB2E has no control over its customers' hardware and many other factors, it is the user's responsibility to perform their own tests to ensure that the product meets their needs.

Thermal Foils & Films

FT_TFO_012_D_30



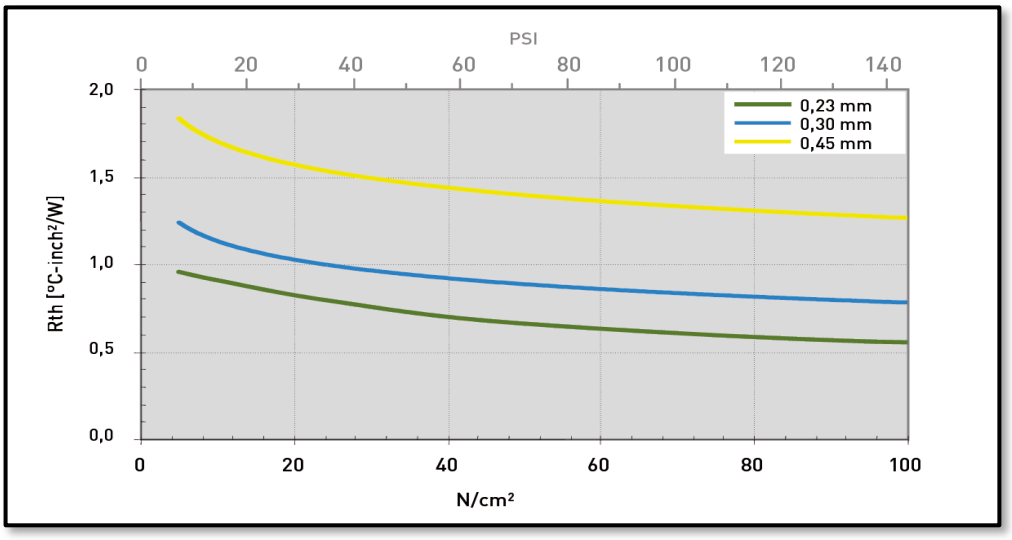
Our Thermal Foams also called Graphic Interfaces are silicone-based thermo-conductive materials that solve the problems of heat dissipation. TFO_012_D is a specially developed heat insulating silicone sheet for applications where low cooling requirements are required. Indeed, it is an excellent thermal conductor of 1.2W/mK, with good thermal resistance facilitating heat transfer and does not have electrical insulation. We can cut according to customer plan. All our mattresses are certified UL 94 in V0.

Application Areas: Electronic components - Electric Vehicles, 5G, Autopilot System, Mobile Phone, AIOT, HPC (High Performance Computing), Server, IC, CPU, MOS, LED ,Mother Board, Power Supply, Heat Sink, LCD-TV, Notebook, PC, Telecom Device,Wireless Hub, DDR Module, etc.

Technical Characteristics

Features	Units	TFO_012_D			
Thickness	mm	0.23	0.30	0.45	-
Reinforcement	-	Fiberglass			
Color	-	Gray			
Tensile strength	kpsi	5.00	4.10	2.90	-
Size	mm	320*1000			Roller 300mm*50m
Resistance @150 Psi	°C-inch²/W	0.55	0.75	1.25	-
Resistance @30 Psi		0.79	1.05	1.55	-
-	-	-			
Thermal Conductivity	W/mK	1.2			
Temperature	°C	-50 to 180			
Breakdown voltage	kV/AC	5.5	> 6.0		-
Volume resistance	0hm - cm	> 1.0 X 10^{11}			
Contante dielectric	@1MHz	6			

The TFO_012_D is available in 0.23/0.30/0.45mm thicknesses.



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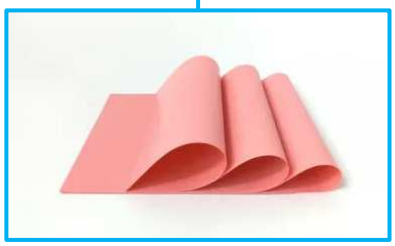
Thermal Foils & Films



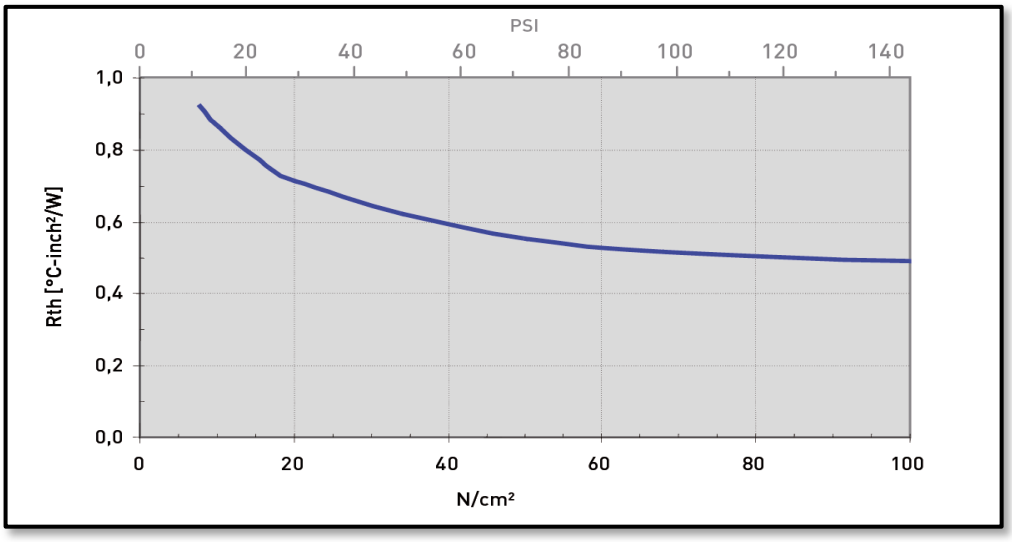
Our Thermal Foams also called Graphic Interfaces are silicone-based thermo-conductive materials that solve the problems of heat dissipation. TFO_016_G is a specially developed heat insulating silicone sheet for applications where low cooling requirements are required. Indeed, it is an excellent thermal conductor of 1.6W/mK, with good thermal resistance facilitating the transfer of heat and which does not have electrical insulation. We can cut according to customer plan. All our mattresses are certified UL 94 in V0.

Application Areas: Electronic components - Electric Vehicles, 5G, Autopilot System, Mobile Phone, AIOT, HPC (High Performance Computing), Server, IC, CPU, MOS, LED ,Mother Board, Power Supply, Heat Sink, LCD-TV, Notebook, PC, Telecom Device,Wireless Hub, DDR Module, etc.

Technical Characteristics

Features	Units	TFO_016_G
Thickness	mm	0.23
Reinforcement	-	Fiberglass
Color	-	Pink
Tensile strength	kpsi	2.9
Size	mm	Roller 290mm*50m
Resistance @150 Psi	°C-inch²/W	0.49
Resistance @30 Psi		0.71
Thermal Conductivity	W/mK	1.6
Temperature	°C	-50 to 180
Breakdown voltage	kV/AC	5.5
Volume resistance	0hm - cm	1.0×10^{11}
Contante dielectric	@1MHz	-

The TFO_016_G is available in 0.23mm thicknesses.



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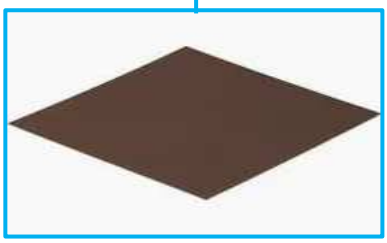
Thermal Foils & Films

FT_TFO_020_J_30



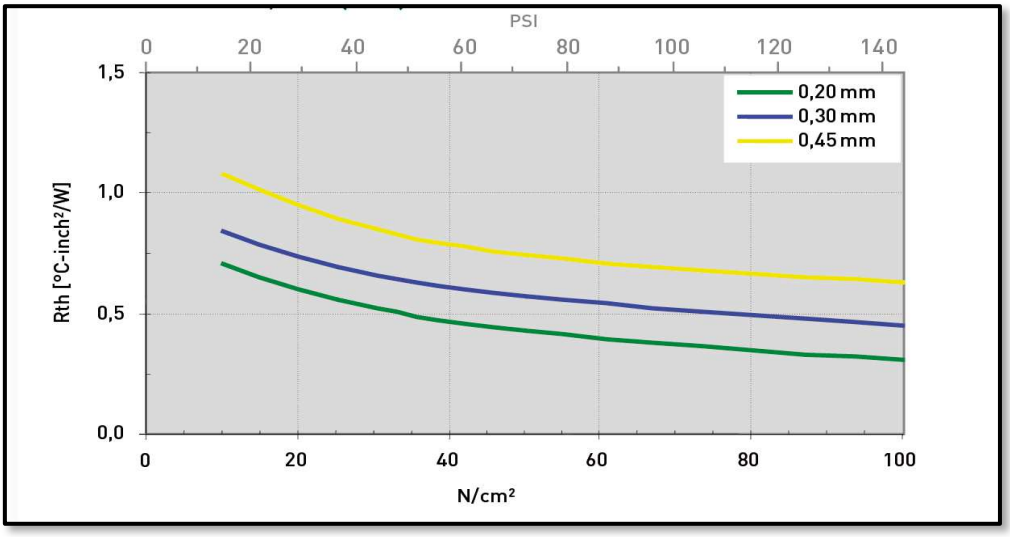
Our Thermal Foams also called Graphic Interfaces are silicone-based thermo-conductive materials that solve the problems of heat dissipation. TFO_020_J is a specially developed heat insulating silicone sheet for applications where a low cooling requirement is required. Indeed, it is an excellent thermal conductor of 2W/mK, with good thermal resistance thus facilitating the transfer of heat and which does not have electrical insulation. We can cut according to customer plan. All our mattresses are certified UL 94 in V0.

Application Areas: Electronic components - Electric Vehicles, 5G, Autopilot System, Mobile Phone, AIOT, HPC (High Performance Computing), Server, IC, CPU, MOS, LED ,Mother Board, Power Supply, Heat Sink, LCD-TV, Notebook, PC, Telecom Device,Wireless Hub, DDR Module, etc.

Technical Characteristics

Features	Units	TFO_020_J			
Thickness	mm	0.20	0.30	0.45	-
Reinforcement	-	FiberGlass			
Color	-	Dark Brown			
Tensile strength	kpsi	5.8	4.0	2.9	-
Size	mm	Roller 300mm x 50M		Roller 300mm x 25M	300*1000
Resistance @150 Psi	°C-inch²/W	0.31	0.45	0.63	-
Resistance @30 Psi		0.61	0.74	0.96	-
Thermal Conductivity	W/mK	2.0			
Temperature	°C	-40 to 180			
Breakdown voltage	kV/AC	5.0	7.0	10.0	-
Volume resistance	0hm - cm	4.2×10^{14}	3.5×10^{14}	3.8×10^{14}	-
Contante dielectric	@1MHz	3.8	4.2	4.3	-

The TFO_020_J is available in 0.20/0.30/0.45/0.80mm thicknesses.



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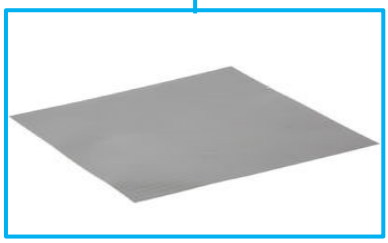
Thermal Foils & Films

FT_TFO_025_K_30



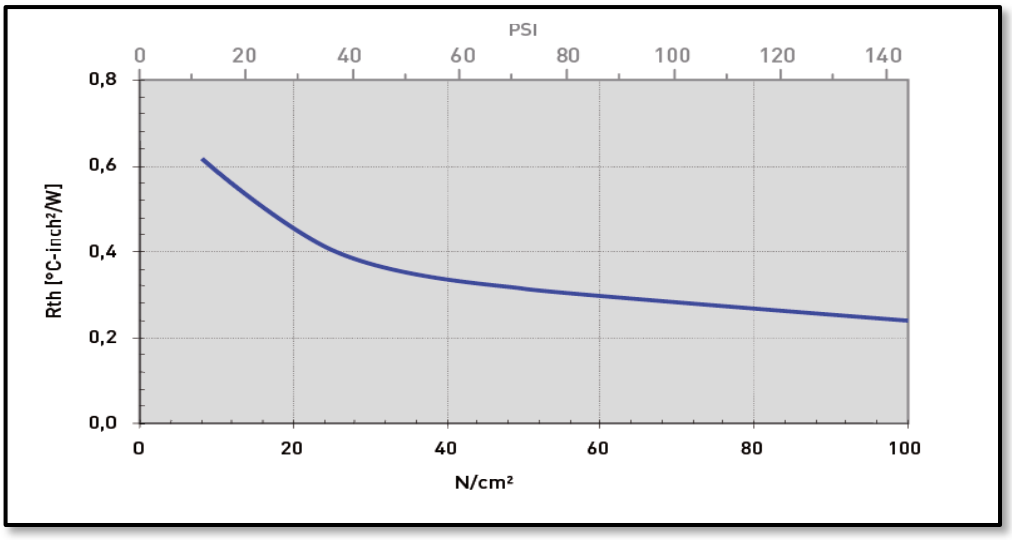
Our Thermal Foams also called Graphic Interfaces are silicone-based thermo-conductive materials that solve the problems of heat dissipation. TFO_025_K is a specially developed heat insulating silicone sheet for applications where low cooling requirements are required. Indeed, it is an excellent thermal conductor of 2.5W/mK, with good thermal resistance facilitating the transfer of heat and which does not have electrical insulation. We can cut according to customer plan. All our mattresses are certified UL 94 in V0.

Application Areas: Electronic components - Electric Vehicles, 5G, Autopilot System, Mobile Phone, AIOT, HPC (High Performance Computing), Server, IC, CPU, MOS, LED ,Mother Board, Power Supply, Heat Sink, LCD-TV, Notebook, PC, Telecom Device,Wireless Hub, DDR Module, etc.

Technical Characteristics

Features	Units	TFO_025_K			
Thickness	mm	0.23	-	-	-
Reinforcement	-	FiberGlass			
Color	-	Gray			
Tensile strength	kpsi	2.9			
Size	mm	320*1000	Roll 320mm x 50M		
Resistance @150 Psi	°C-inch²/W	0.24			
Resistance @30 Psi		0.47			
Thermal Conductivity	W/mK	2.5			
Temperature	°C	-50 to 200			
Breakdown voltage	kV/AC	2			
Volume resistance	0hm - cm	2×10^{14}			
Contante dielectric	@1MHz	4			

The TFO_025_K is available in 0.23 mm thickness.



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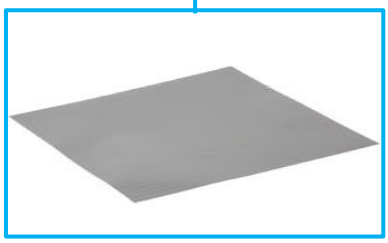
Thermal Foils & Films

FT_TFO_030_O_30



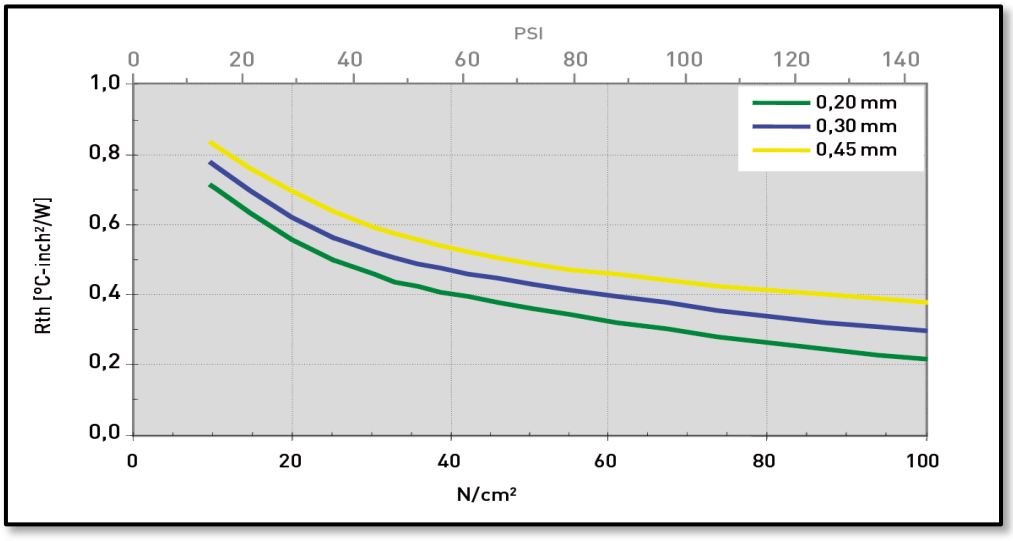
Our Thermal Foams also called Graphic Interfaces are silicone-based thermo-conductive materials that solve the problems of heat dissipation. TFO_030_O is a specially developed heat insulating silicone sheet for applications where low cooling requirements are required. Indeed, it is an excellent thermal conductor of 3W/mK, with good thermal resistance thus facilitating the transfer of heat and which does not have electrical insulation. We can cut according to customer plan. All our mattresses are certified UL 94 in V0.

Application Areas: Electronic components - Electric Vehicles, 5G, Autopilot System, Mobile Phone, AIOT, HPC (High Performance Computing), Server, IC, CPU, MOS, LED ,Mother Board, Power Supply, Heat Sink, LCD-TV, Notebook, PC, Telecom Device,Wireless Hub, DDR Module, etc.

Technical Characteristics

Features	Units	TFO_030_O			
Thickness	mm	0.20	0.30	0.45	-
Reinforcement	-	Fiberglass			
Color	-	Gray			
Tensile strength	kpsi	3.3	2.3	1.6	
Size	mm	Roll 300mm x 50M		Roll 300mm x 25M	Sheet
Resistance @150 Psi	°C-inch²/W	0.22	0.30	0.38	-
Resistance @30 Psi		0.55	0.60	0.70	-
Thermal Conductivity	W/mK	3.0			
Temperature	°C	-40 to 180			
Breakdown voltage	kV/AC	5.0	7.0	8.0	-
Volume resistance	0hm - cm	9.2×10^{13}	8.8×10^{13}	3.4×10^{12}	-
Contante dielectric	@1MHz	4.8	5.6	6.2	-

The TFO_030_O is available in 0.20/0.30/0.45mm thicknesses.



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Thermal Foils & Films

FT_TFO_041_T_30

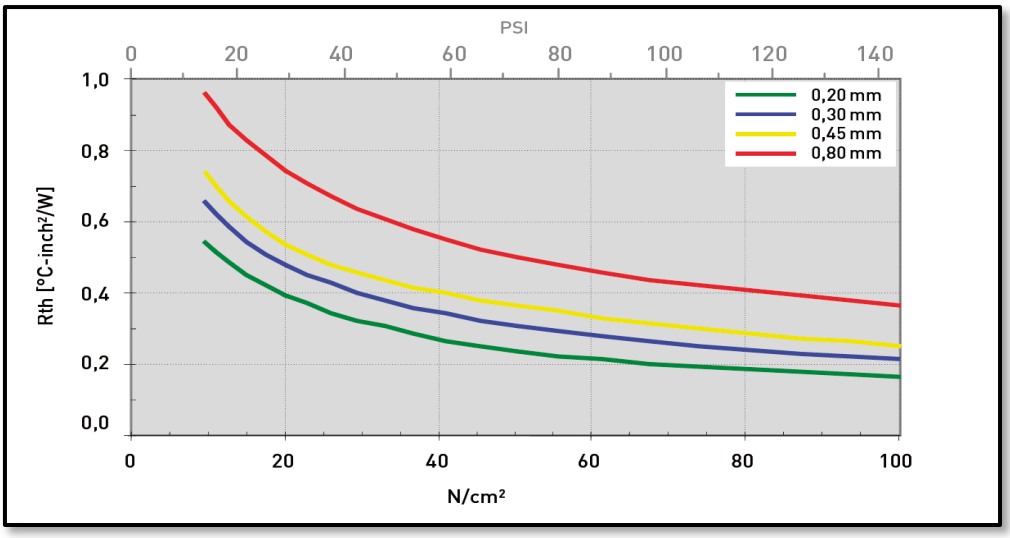
Our Thermal Foams also called Graphic Interfaces are silicone-based thermo-conductive materials that solve the problems of heat dissipation. TFO_041_T is a specially developed heat insulating silicone sheet for applications where low cooling requirements are required. Indeed, it is an excellent thermal conductor of 4.1W/mK, with good thermal resistance facilitating the transfer of heat and does not have electrical insulation. We can cut according to customer plan. All our mattresses are certified UL 94 in V0.

Application Areas: Electronic components - Electric Vehicles, 5G, Autopilot System, Mobile Phone, AIOT, HPC (High Performance Computing), Server, IC, CPU, MOS, LED ,Mother Board, Power Supply, Heat Sink, LCD-TV, Notebook, PC, Telecom Device,Wireless Hub, DDR Module, etc.

Technical Characteristics

Features	Units	TFO_041_T			
Thickness	mm	0.20	0.30	0.45	0.80
Reinforcement	-	Fiberglass			
Color	-	Gray		White	
Tensile strength	kpsi	3.6	2.9	2.0	1.3
Size	mm	440*510			
Resistance @150 Psi	°C-inch²/W	0.16	0.21	0.24	0.36
Resistance @30 Psi		0.39	0.47	0.53	0.74
Thermal Conductivity	W/mK	4.1			
Temperature	°C	-50 to 200			
Breakdown voltage	kV/AC	3.0	6.5	9.0	> 10
Volume resistance	0hm - cm	1.9×10^{15}	2.4×10^{15}	3.3×10^{15}	4.1×10^{15}
Contante dielectric	@1MHz	3.6			

The TFO_041_T is available in 0.20/0.30/0.45/0.80mm thicknesses.



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Thermal Foils & Films

FT_TFO_050_X_30

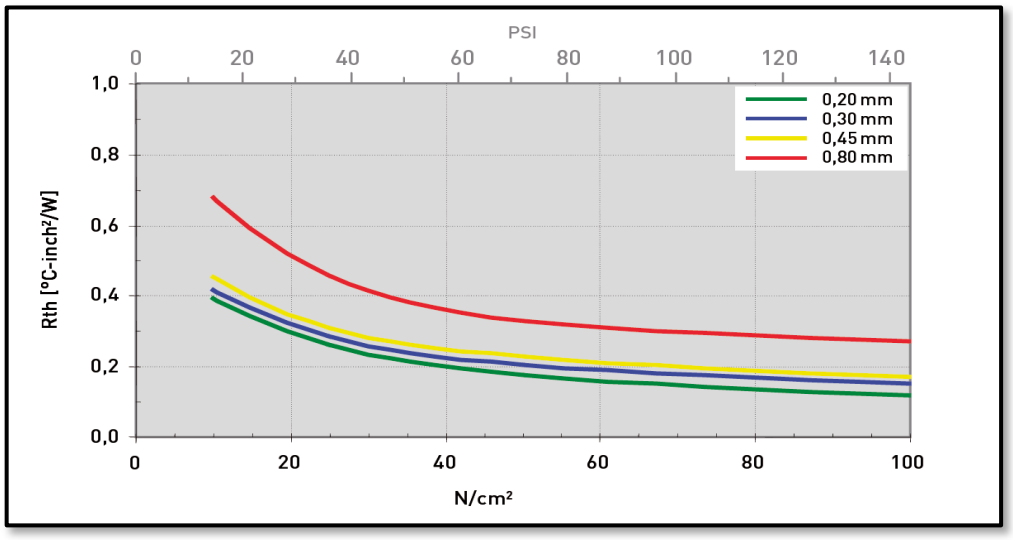
Our Thermal Foams also called Graphic Interfaces are silicone-based thermo-conductive materials that solve the problems of heat dissipation. The TFO_050_X is a specially developed heat insulating silicone sheet for applications where low cooling requirements are required. Indeed, it is an excellent thermal conductor of 5.0W/mK, with good thermal resistance facilitating heat transfer and does not have electrical insulation. We can cut according to customer plan. All our mattresses are certified UL 94 in V0.

Application Areas: Electronic components - Electric Vehicles, 5G, Autopilot System, Mobile Phone, AIOT, HPC (High Performance Computing), Server, IC, CPU, MOS, LED ,Mother Board, Power Supply, Heat Sink, LCD-TV, Notebook, PC, Telecom Device,Wireless Hub, DDR Module, etc.

Technical Characteristics

Features	Units	TFO_050_X			
Thickness	mm	0.20	0.30	0.45	0.80
Reinforcement	-	Fiberglass			
Color	-	White			
Tensile strength	kpsi	1.3	1.2	0.7	0.6
Size	mm	440*510			
Resistance @150 Psi	°C-inch²/W	0.11	0.15	0.17	0.27
Resistance @30 Psi		0.29	0.32	0.35	0.52
Thermal Conductivity	W/mK	5.0			
Temperature	°C	-50 to 200			
Breakdown voltage	kV/AC	3.0	6.0	9.0	> 10
Volume resistance	0hm - cm	1.7×10^{15}	7.9×10^{15}	9.2×10^{15}	8.9×10^{15}
Contante dielectric	@1MHz	3.3			

The TFO_050_X is available in 0.20/0.30/0.45/0.80mm thicknesses.



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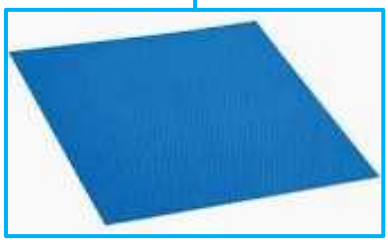
Thermal Foils & Films

FT_TFO_018_AB_NS_07



Our thermal electrical insulation materials also called thermal interfaces are silicone-free thermo-conductive materials that solve the problems of heat dissipation. The TFO_018_AB_NS is a heat insulating sheet specially developed for applications where a high cooling need is required. Indeed, this is an excellent thermal conductor of 1.8W/mK, with good thermal resistance facilitating the transfer of heat and which does not have electrical insulation. We can cut according to customer plan. All our mattresses are certified UL 94 in V0.

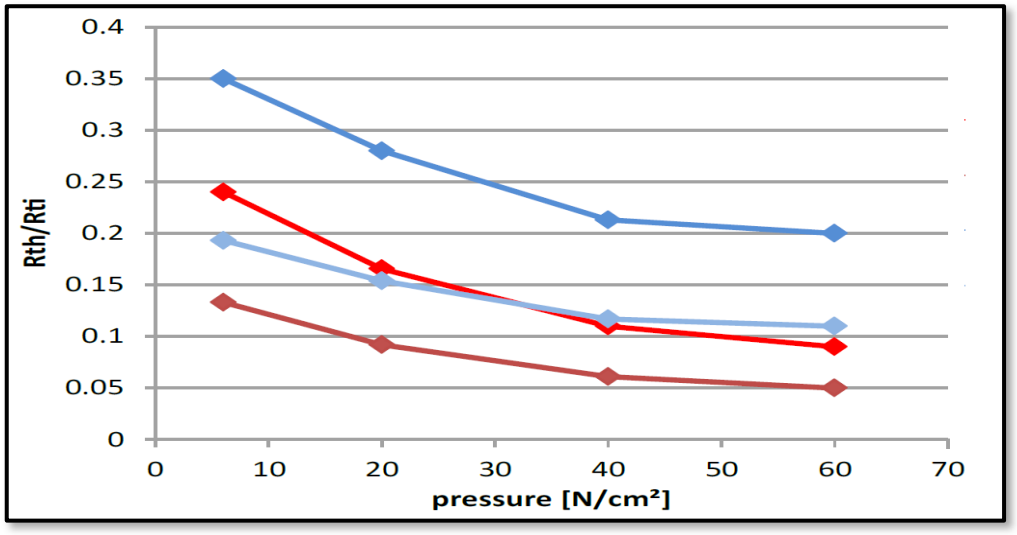
Application Areas: Electronic components - Electric Vehicles, 5G, Autopilot System, Mobile Phone, AIOT, HPC (High Performance Computing), Server, IC, CPU, MOS, LED ,Mother Board, Power Supply, Heat Sink, LCD-TV, Notebook, PC, Telecom Device,Wireless Hub, DDR Module, etc.

Technical Characteristics

Features	Units	TFO_018_AB_NS
Thickness	mm	0.15/0.3
Density	g/cm3	2.26
Color	-	Blue
Hardness	Shore A	80 - 90
Tensile Strength	N/mm²	3.0
Elongation	%	130
Resistance @60 Psi	K/W	0.20
Resistance @30 Psi		0.25
Resistance @10 Psi		0.35
Thermal Conductivity	W/mK	1.8
Temperature	°C	-40 to + 125
Volume resistance	0hm - cm	1.4×10^{14}
Dielectric constant	@1MHz	3.2
Breakdown Voltage	kV	4

TFO-018_AB_NS is available in 0.15/0.30mm thicknesses.

TFO-018_AB_NS (Rth [Kin²/W]) *TFO-018_AB_NS (Rth [K/W])*



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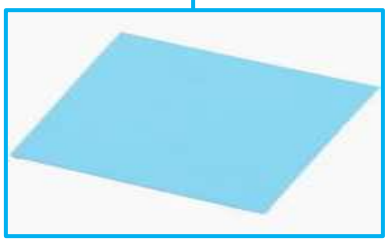
Thermal Foils & Films

FT_TFO_030_AB_NS_07



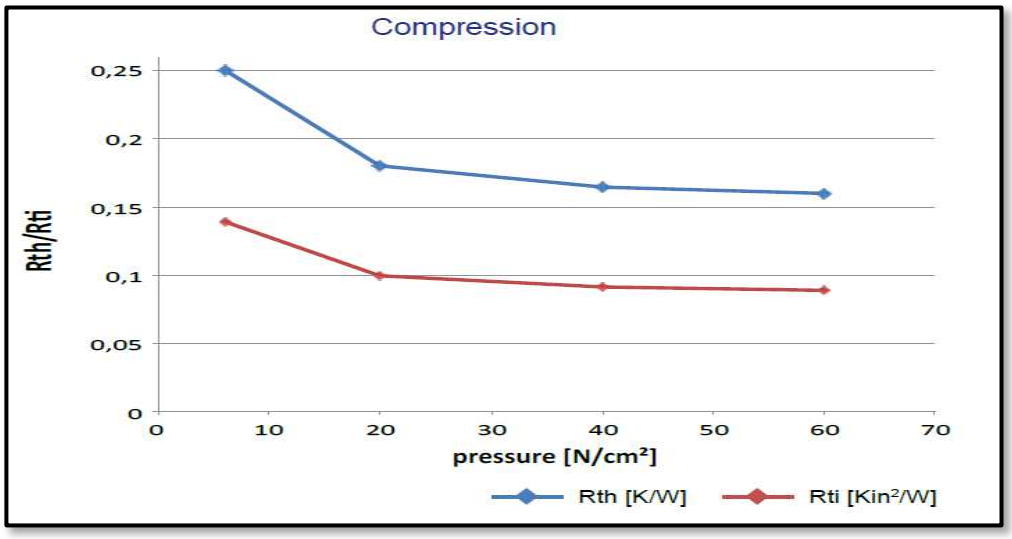
Our thermal electrical insulation materials also called thermal interfaces are silicone-free thermo-conductive materials that solve the problems of heat dissipation. The TFO_030_AB_NS is a specially developed heat insulating sheet for applications where a high cooling need is required. Indeed, it is an excellent thermal conductor of 3.0W/mK, with good thermal resistance facilitating the transfer of heat and does not have electrical insulation. We can cut according to customer plan. All our mattresses are certified UL 94 in V0.

Application Areas: Electronic components - Electric Vehicles, 5G, Autopilot System, Mobile Phone, AIOT, HPC (High Performance Computing), Server, IC, CPU, MOS, LED ,Mother Board, Power Supply, Heat Sink, LCD-TV, Notebook, PC, Telecom Device,Wireless Hub, DDR Module, etc.

Technical Characteristics

Features	Units	TFO_030_AB_NS
Thickness	mm	0.2
Density	g/cm3	1.44
Color	-	Light blue
Hardness	Shore A	70 - 85
Tensile strength	N/mm²	1.0
Elongation	%	50
Resistance @60 Psi	K/W	0.16
Resistance @30 Psi		0.18
Resistance @10 Psi		0.23
Thermal Conductivity	W/mK	3.0
Temperature	°C	-40 to + 150
volume resistance	0hm - cm	4.1×10^9
Dielectric contant	@1MHz	2
Breakdown voltage	kV	4

TFO_030_AB_NS is available in 0.2mm thickness.



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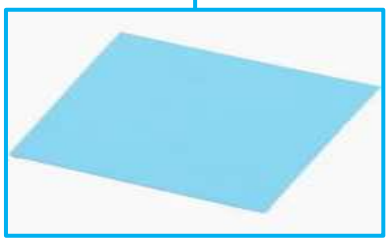
Thermal Foils & Films

FT_TFO_060_AB_NS_07



Our thermal electrical insulation materials also called thermal interfaces are silicone-free thermo-conductive materials that solve the problems of heat dissipation. The TFO_060_AB_NS is a specially developed heat insulating sheet for applications where a high cooling need is required. Indeed, it is an excellent thermal conductor of 6.0W/mK, with good thermal resistance facilitating the transfer of heat and which does not have electrical insulation. We can cut according to customer plan. All our mattresses are certified UL 94 in V0.

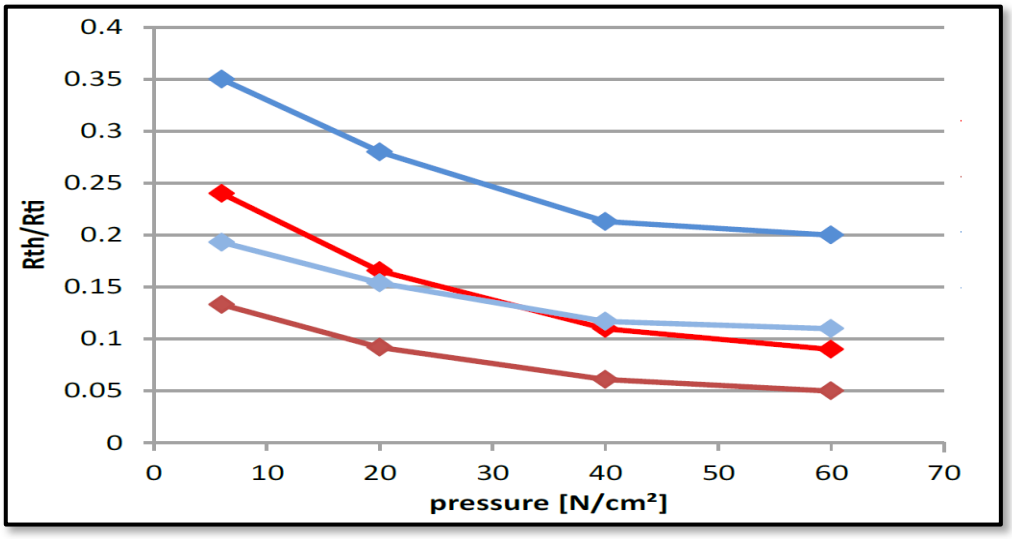
Application Areas: Electronic components - Electric Vehicles, 5G, Autopilot System, Mobile Phone, AIOT, HPC (High Performance Computing), Server, IC, CPU, MOS, LED ,Mother Board, Power Supply, Heat Sink, LCD-TV, Notebook, PC, Telecom Device,Wireless Hub, DDR Module, etc.

Technical characteristics

Features	Units	TFO_060_AB_NS
Thickness	mm	0.1/0.3
Density	g/cm3	1.46
Color	-	Light Blue
Hardness	Shore A	70 - 85
Tensile Strength	N/mm²	2.0
Elongation	%	150
Resistance @60 Psi	K/W	0.09
Resistance @30 Psi		0.14
Resistance @10 Psi		0.24
Thermal Conductivity	W/mK	3.0
Temperature	°C	-40 to + 125
Volume resistance	0hm - cm	2.0×10^{11}
Dielectric Constant	@1MHz	3.1
Breakdown Voltage	kV	4

TFO_060_AB_NS is available in 0.1/0.30mm thicknesses.

TFO-060_AB_NS (Rth [Kin²/W]) ***TFO-060_AB_NS (Rth [K/W])***



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